| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 126 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 10:01 |
| 2 | 0 | 438/14,15,762,763.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 10:02 |
| 3 | 32 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 10:03 |
| – | 6039 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/30 15:08 |
| – | 0 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bomds) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/30 15:10 |
| – | 184 | (integrated adj circuit) and (contact or output/input adj pads) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/30 15:15 |
| – | 118 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 10:15 |
| – | 118 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 10:25 |
| – | 0 | "09888674" and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 15:37 |
| – | 0 | "09888674" and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 10:14 |
| – | 0 | "09/888674" and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 11:45 |
| – | 118 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 09:59 |
| – | 0 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder adj bonds) and (wire adj bonds) and (barrier) and (passivation) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 12:24 |
| – | 0 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder adj bonds) and (wire adj bonds) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 12:25 |
| – | 4 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire adj bonds) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 12:26 |
| – | 28 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/02/01 15:10 |

| - | 118 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/01/31 15:38 |
|---|---|---|---|---|
| - | 23 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 10:03 |
| - | 0 | 438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:38 |
| - | 0 | 438/15,762,763.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/07/07 10:01 |
| - | 4 | 257/737.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:41 |
| - | 27 | (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:01 |
| - | 0 | 438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:44 |
| - | 123 | (integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:41 |
| - | 4 | 257/737.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:51 |
| - | 0 | 438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 18:45 |
| - | 8 | 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 19:03 |
| - | 4 | 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/30 19:04 |
| - | 36 | (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/31 11:42 |
| - | 4 | (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adj layer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/05/31 11:43 |
| - | 0 | "6221682" and gold | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 13:21 |
| - | 0 | "20010011764" and gold | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 13:52 |
| - | 2 | "20010011764" | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 13:52 |

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|---|---|---|---|---|
| – | 0 | "6441487" and (gold) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 15:37 |
| – | 9 | "5234149" and (gold) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 15:38 |
| – | 6 | "5234149" and (under adj bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 19:18 |
| – | 0 | 5234149.pn. and (under adj bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 17:48 |
| – | 1 | "20010011764" and (under adj bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 19:18 |
| – | 1 | "20010011764" and (electroplating) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/19 19:19 |
| – | 10 | "5234149" and (reflow$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 10:15 |
| – | 0 | 5234149.pn. and (reflow$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 10:16 |
| – | 1 | 20010011764.pn. and (reflow$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 10:31 |
| – | 1 | 20010011764.pn. and (lead) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 10:34 |
| – | 1 | 20010011764.pn. and (reflow$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 11:05 |
| – | 0 | 20010011764.pn. and (selective adj electroplating) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/06/20 11:05 |